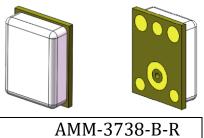
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Specifications

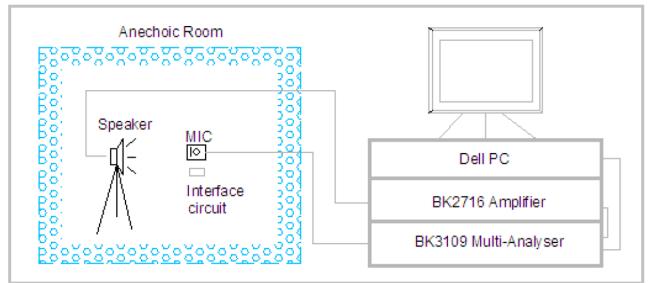
Parameters	Values	Units
Sensitivity (1 kHz @ 50cm)		
0 dB=1V/Pa	-38±1	dB
Rated Voltage	2	VDC
Operating Voltage Range	1.5 to 3.6	VDC
Output Impedance (@ 1 kHz)	300	Ω
Current consumption (at 2 VDC/at 3.6 VDC)	90/200	μΑ
Signal-to-Noise Ratio (1kHz, 94 dB input, A-weighted)	62	dB
Decreasing Voltage		
(0 dB=1V/Pa, 3.6 to 1.5 VDC)	0.5	dB
Frequency Range	20 - 20,000	Hz
Total Harmonic Distortion		
(94 dB @ 50cm, 1 kHz)	0.5%	-
Acoustic Overload Point (AOP) (50cm, 1kHz, 10% THD)	125	dB
Directivity	Omi	nidirectional
Acceptable Soldering Methods	Reflow Solder	See page 4 for soldering information
Environmental Compliances	RoHS	/Halogen Free
Power Supply Rejection (PSR, 100 mVpp Square Wave @ 217 Hz, A-weighted)	-90	dB
Weight	<0.3	Grams
Operating Temperature (VDD < 3 VDC)	-40 ~ +100	°C
Operating Temperature (VDD > 3 VDC)	-40 ~ +70	°C
Storage Temperature	-40 ~ +125	°C
MSL (Moisture Sensitivity Level)*	1	-

*MSL level dependent on product remaining in sealed packaging until use

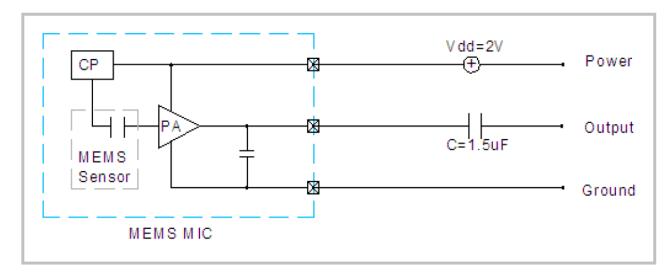
Absolute Maximum Ratings

Parameters	Values	Units	
Max Voltage on Any Pin	4	VDC	
Max Sound Pressure Level	160	dB	
Max Mechanical Shock	10,000	Gs	
Max Vibration	Pre-MIL-STD-883 Method 2007, Test Condition B		

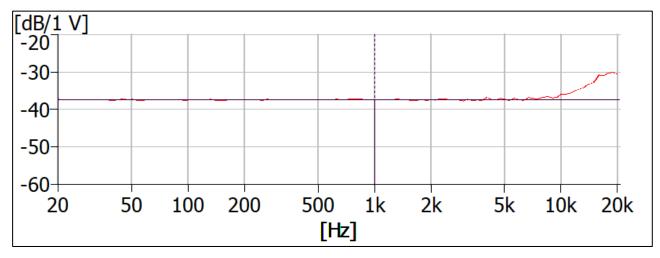
Measurement Method (with speaker spaced 50cm from microphone)

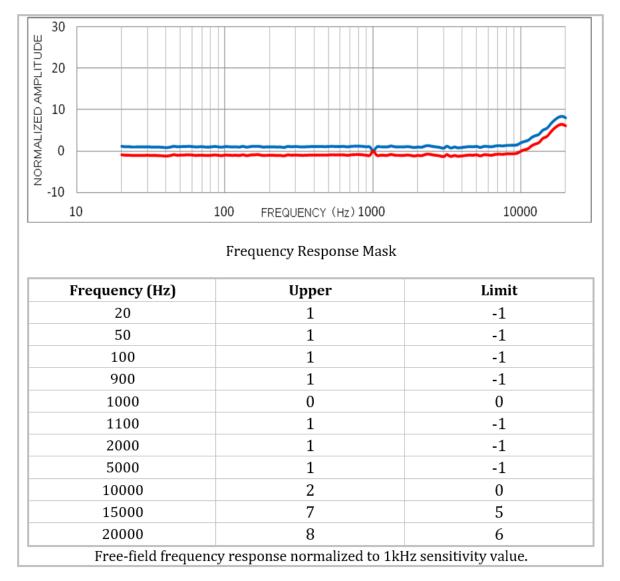


Recommended Drive Circuit



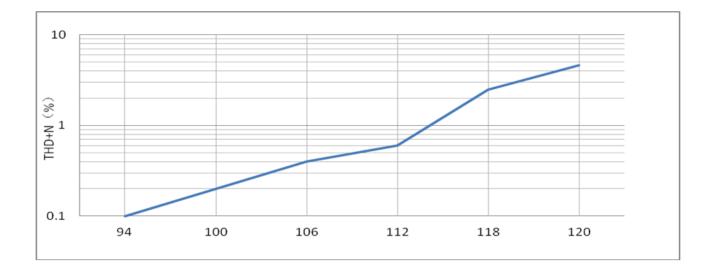
Typical Frequency Response



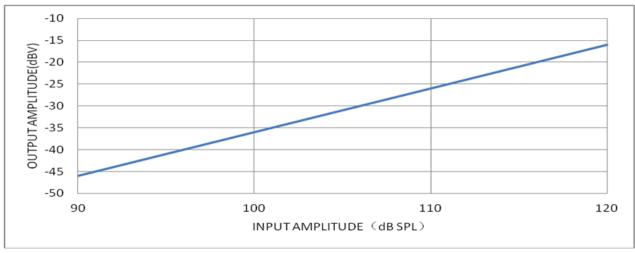


Frequency Response Mask (100% Pass/Fail Test for Microphones)

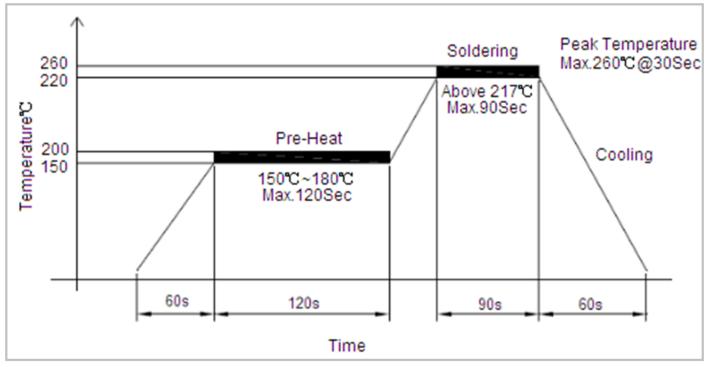
Total Harmonic Distortion + Noise versus SPL Input (with acoustic source at 50cm)



Microphone Output versus SPL Input (with acoustic source at 50cm)



Recommended Soldering Procedure



Important Notes in order to minimize device damage:

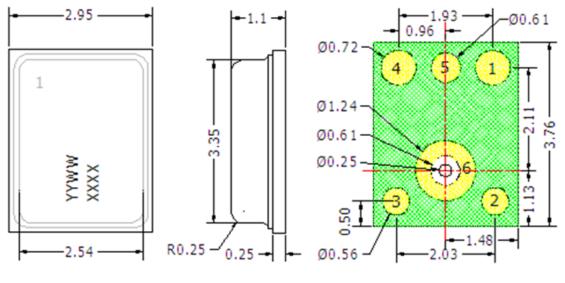
- 1. Do not boards wash or clean after the reflow process.
- 2. Do not apply over 0.3Mpa of air pressure into the port hole.
- 3. Do not expose to ultrasonic processing or cleaning.
- 4. Do not pull a vacuum over port hole of the microphone.

Re	liab	ilitv	Test	ing

Type of Test	Test Specifications
Simulated Reflow (Without Solder)	Samples for qualification testing require 3 passes 260±5 °C reflow solder profiles. 2 hours of setting time is required between each reflow profile test.
Static Humidity	Precondition at +25°C for 1 hour. Expose to +85°C with 85% relative humidity for 1000 hours. Finally, dry at room ambient for 3±1 hour before taking final measurement.
Temperature Shock	Each cycle shall consist of 30 minutes at -40°C, 30 minutes at +125°C with 5 minutes transition time. Test duration is for 30 cycles, starting from cold to hot temperature.
ESD Sensitivity	Perform ESD sensitivity threshold measurements for each contact according to MIL-STD-883G, Method 3015.7 for Human Body Model. Identify the ESD threshold levels indicating passage of 8000V Human Body Model.
Vibration Test	Vibrate randomly along three perpendicular directions for 30 minutes in each direction, 4 cycles from 20~2000 Hz with a peak acceleration of 20 Gs.
Shock Test	Subject samples to half-sine shock pulses (3000±15% Gs for 0.3ms) in each direction, for a total of 18 shocks.
Drop Test	Drop samples from 1.5m height onto a steel surface, total 18 times and inspected for mechanical damage.
Operation Life	Subject samples to +125°C for 168 hours under full maximum rated voltage.

Microphone frequency response and sensitivity shall not deviate more than ±3 dB.

Dimensions



Top View

Side View

Bottom View

Data Code		
YYWW YY:Year WW: Work Week		
XXXX	XXXX: Lot No.	

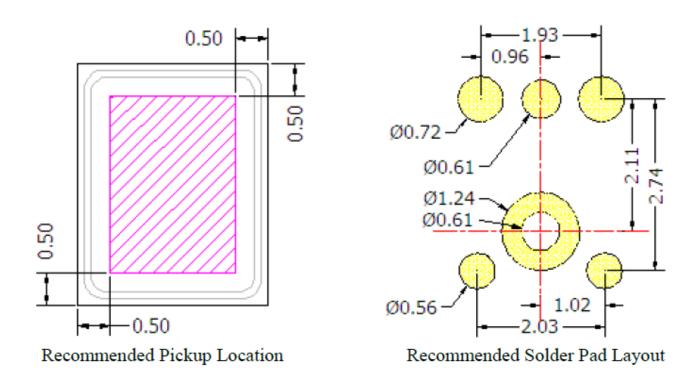
Item	Dimension	Tolerance (+/-)	Units
Length(L)	3.76	0.10	mm
Width(W)	2.95	0.10	mm
Height(H)	1.1	0.10	mm
Acoustic Port (AP)	Ø0.25	0.05	mm

Pin #	Pin Name	Туре	Description
1	Output	Signal	Output Signal
2	GND	Ground	Ground
3	GND	Ground	Ground
4	Vdd	Power	Power Supply
5	GND	Ground	Ground
6	GND	Ground	Ground

Notes:

All dimensions are in millimeter (mm). Tolerance ±0.15mm unless otherwise specified.

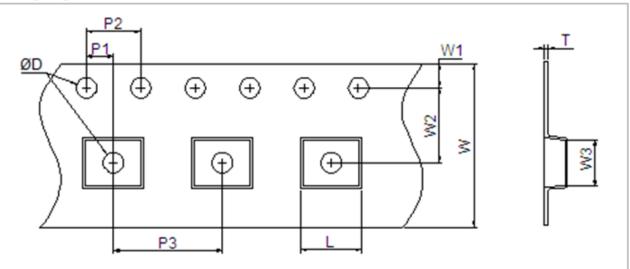
Suggested Pickup Tool Location and Land Pattern*



*This land pattern is advisory only and its use or adaptation is entirely voluntary. PUI Audio disclaims all liability of any kind associated with the use, application, or adaptation of this land pattern.

Packaging

Tape Specification

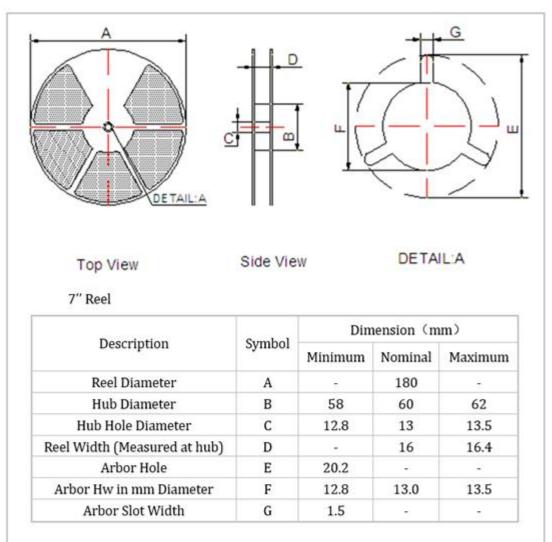


Sumbol		Dimension			
Symbol	Minimum	Nominal	Maximum		
ØD	1.5	1.5	1.6		
P1	1.9	2.0	2.1		
P2	3.9	4.0	4.1		
P3	7.9	8.0	8.1		
L	4.0	4.1	4.2		
W	11.7	12	12.3		
W1	1.65	1.75	1.85		
W2	5.4	5.5	5.6		
W3	3.3	3.4	3.5		
Т	0.25	0.3	0.35		

Notes All dimensions are in millimeter (mm). Tolerance±0.15mm unless otherwise specified.

Packaging (continued)

Reel Specification



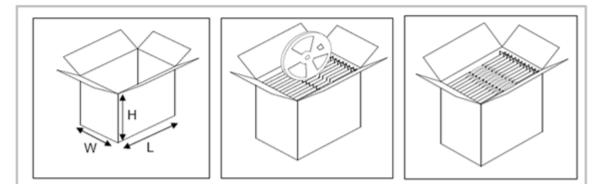
Notes All dimensions are in millimeter (mm).

Packaging (continued)

Packing Quantity

7" Reel Packing		
Leader 32units		
00)00	0000)00	00)0000
		o(oo
MEMS Microphone	AP Hole Lo	cation

Packing Information



Tape & Reel 7"

Qty/reel	Weight/reel	Reel/Carton	Qty/carton	Weight full	Dimension carton Box	Storage
Pcs	Kg	Nos	Nos	Load(kg)	(L x W x H) mm	Temp
1250	0.25	4	5000	~3.00	272 x 159 x 236	-10°C~50 °C

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Revision	Description	Date	
-	Released from Engineering	10/31/2019	

Note:

- 1. Unless otherwise specified:
 - A. All dimensions are in millimeters.
 - B. Default tolerances are ± 0.5 mm and angles are $\pm 3^{\circ}$.
- 2. Specifications subject to change or withdrawal without notice.